Special Issue

Advances in Additive Manufacturing of 2D/3D Electronic Applications

Message from the Guest Editors

The new form of industrial production is demanding the generation of new, intelligent manufacturing processes which are more customizable, resuting in smaller production batches and more waste. Additive manufacturing (AM) is seen as a powerful enabler for circular economy, which allows materials to be used as long as possible. Thanks to efforts in both the academic and industrial arenas, more and more advanced technologies and applications in AM have been explored. This Special Issue is devoted to electronics applications of AM technologies. Printed electronics and 3D printing are typical AM technologies. In addition, more hybrid technologies have been developed. Thus, authors are welcome to demonstrate the benefit of integrating AM and materials development technologies into other advanced manufacturing approaches. Both in situ and post-processing technologies have been developed to fabricate electronic components, which can be applied into the development of functional devices, such as circuits, sensors, flexible electronis, wearable electronics, etc. Applications can range from the microscale to the macroscale and from research to industry.

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As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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